

**1M-BIT CMOS FAST STATIC RAM
128K-WORD BY 9-BIT**

Description

The μ PD431009 is a high speed, low power, 1 179 072 bits (131 072 words by 9 bits) CMOS static RAM.
The μ PD431009 is packed in 36-pin plastic SOJ.

Feature

- 131 072 words by 9 bits organization
- Fast access time 15, 17, 20 ns (MAX.)
- Output buffers control: \overline{OE}
- Common I/O using three state outputs
- Fully static operation: no clock or refreshing to operate
- TTL compatible: all inputs and outputs
- Single +5 V power supply

Ordering Information

Part number	Package	Access time ns (MAX.)	Operating supply current mA (MAX.)	Standby supply current mA (MAX.)	Quality grade
μ PD431009LE-15	36-pin plastic SOJ (400 mil)	15	160	10	Standard
μ PD431009LE-17		17	150		
μ PD431009LE-20		20	140		

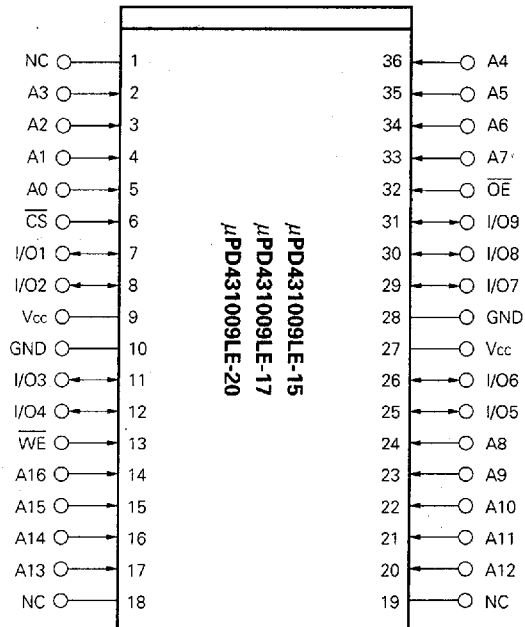
Remark Operating supply current is 120 mA (MAX.) when this product is used at 50ns cycle time.

Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

The information in this document is subject to change without notice.

Pin Configuration (Marking Side)

36-Pin Plastic SOJ (400 mil)



- A0 to A16 : Address Inputs
- I/O1 to I/O9 : Data Inputs/Outputs
- \overline{CS} : Chip Select
- \overline{WE} : Write Enable
- \overline{OE} : Output Enable
- Vcc : Power Supply
- GND : Ground
- NC : No Connection

Electrical Specifications

Absolute Maximum Ratings

Parameter	Symbol	Rating	Unit
Supply voltage	V _{CC}	-0.5 ^{Note} to +7.0	V
Input/Output voltage	V _I	-0.5 ^{Note} to V _{CC} +0.5	V
Operating temperature	T _{opt}	0 to +70	°C
Storage temperature	T _{stg}	-55 to +125	°C

Note -3.0 V (MIN.) (Pulse width: 10 ns)

Recommended Operating Conditions

Parameter	Symbol	MIN.	TYP.	MAX.	Unit
Supply voltage	V _{CC}	4.5	5.0	5.5	V
High level input voltage	V _{IH}	2.2		V _{CC} +0.5	V
Low level input voltage	V _{IL}	-0.5 ^{Note}		+0.8	V
Ambient temperature	T _a	0		+70	°C

Note -3.0 V (MIN.) (Pulse width: 10 ns)

DC Characteristics (Recommended operating conditions unless otherwise noted)

Parameter	Symbol	Test conditions	MIN.	TYP.	MAX.	Unit
Input leakage current	I _{LI}	V _{IN} = 0 V to V _{CC}	-2		+2	μA
Output leakage current	I _{LO}	V _{VO} = 0 V to V _{CC} , $\overline{CS} = V_{IH}$ or $\overline{OE} = V_{IH}$ or $\overline{WE} = V_{IL}$	-2		+2	μA
Operating supply current	I _{CC}	$\overline{CS} = V_{IL}$, I _{I/O} = 0 mA			160	mA
			Cycle time: 15 ns		150	
			Cycle time: 20 ns		140	
			Cycle time: 50 ns		120	
Standby supply current	I _{SB}	$\overline{CS} = V_{IH}$, V _{IN} = V _{IH} or V _{IL}			30	mA
	I _{SB1}	V _{CC} - 0.2 V ≤ \overline{CS} , V _{IN} ≤ 0.2 V or V _{CC} - 0.2 V ≤ V _{IN}			10	
High level output voltage	V _{OH}	I _{OH} = -4.0 mA	2.4			V
Low level output voltage	V _{OL}	I _{OL} = 8 mA			0.4	V

Remark V_{IN}: Input voltage

Capacitance (T_a = +25 °C, f = 1 MHz)

Parameter	Symbol	Test conditions	MIN.	TYP.	MAX.	Unit
Input capacitance	C _{IN}	V _{IN} = 0 V			6	pF
Input/Output capacitance	C _{I/O}	V _{VO} = 0 V			8	pF

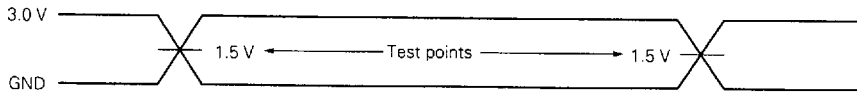
Remark 1. V_{IN}: Input voltage

2. These parameters are periodically sampled and not 100 % tested.

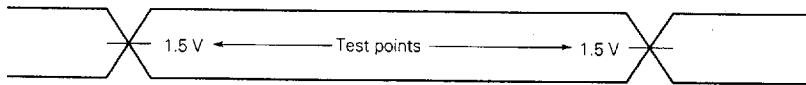
AC Characteristics (Recommended operating conditions unless otherwise noted)

AC Test Conditions

Input waveform (Rise/fall time ≤ 3 ns)



Output waveform



Output load

AC Characteristics directed with the note should be measured with the output load shown in Fig. 1 or Fig. 2.

Fig. 1

(For tAA, tACS, tOE, tOH)

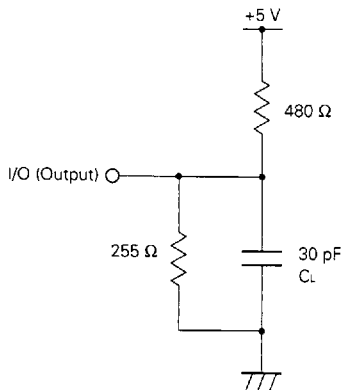
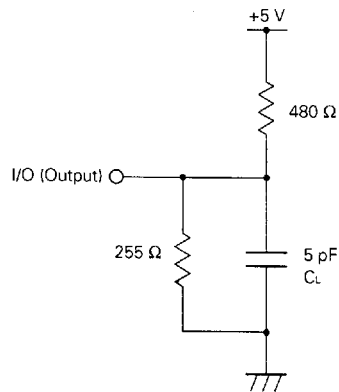


Fig. 2

(For tCHZ, tCLZ, tOHZ, tOLZ, tWHZ, tOW)



Remark CL includes capacitances of the probe and jig, and stray capacitances.

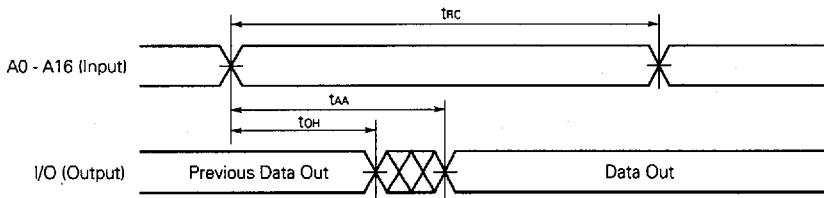
Read Cycle

Parameter	Symbol	μPD431009LE-15		μPD431009LE-17		μPD431009LE-20		Unit	Condition
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Read cycle time	t _{RC}	15		17		20		ns	
Address access time	t _{AA}		15		17		20	ns	Note 1.
CS access time	t _{ACS}		15		17		20	ns	
OE access time	t _{OE}		8		9		10	ns	
Output hold from address change	t _{OH}	5		5		5		ns	Note 2.
CS to output in low-Z	t _{CLZ}	5		5		5		ns	
OE to output in low-Z	t _{OLZ}	1		1		1		ns	
CS to output in high-Z	t _{CHZ}		7		7		7	ns	
OE to output in high-Z	t _{OHZ}		7		7		7	ns	

Note 1. See the output load shown in Fig. 1.

2. See the output load shown in Fig. 2.

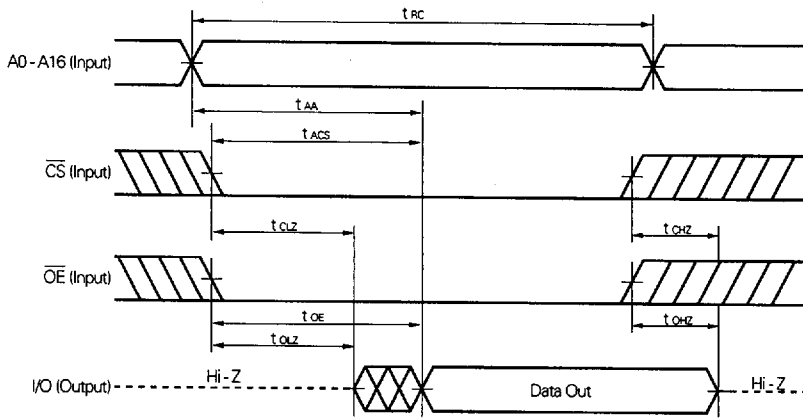
Read Cycle Timing Chart 1 (Address Access)



Remark 1. In read cycle, \overline{WE} should be fixed to high level.

2. $\overline{CS} = \overline{OE} = V_{IL}$

Read Cycle Timing Chart 2 (\overline{CS} Access)



Caution Address valid prior to or coincident with \overline{CS} low level input.

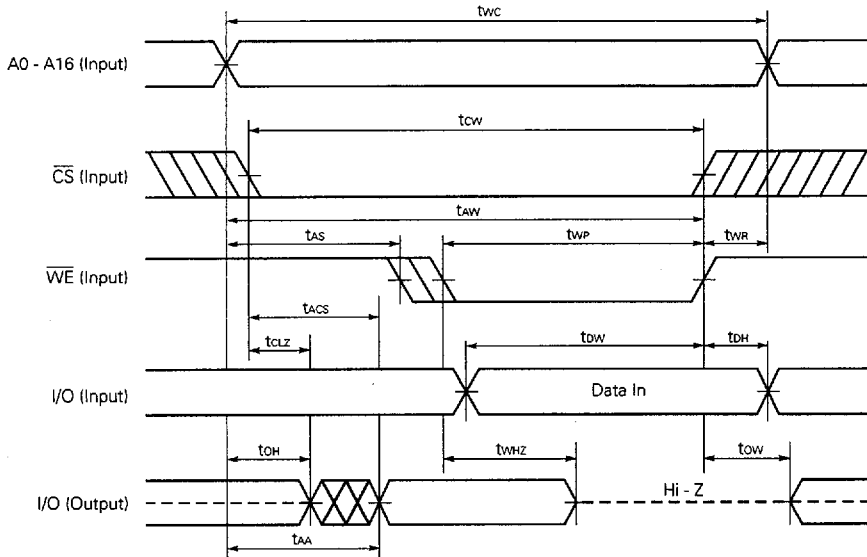
Remark In read cycle, \overline{WE} should be fixed to high level.

Write Cycle

Parameter	Symbol	μPD431009LE-15		μPD431009LE-17		μPD431009LE-20		Unit	Condition
		MIN.	MAX.	MIN.	MAX.	MIN.	MAX.		
Write cycle time	t _{wc}	15		17		20		ns	
\overline{CS} to end of write	t _{cw}	10		11		12		ns	
Address valid to end of write	t _{aw}	9		11		12		ns	
Write pulse width	t _{wp}	9		10		10		ns	
Data valid to end of write	t _{dw}	8		9		10		ns	
Data hold time	t _{dh}	0		0		0		ns	
Address setup time	t _{as}	0		0		0		ns	
Write recovery time	t _{wr}	0		0		0		ns	
\overline{WE} to output in high-Z	t _{whz}		7		7		7	ns	Note
Output active from end of write	t _{ow}	3		3		3		ns	

Note See the output load shown in Fig. 2.

Write Cycle Timing Chart 1 (\overline{WE} Controlled)



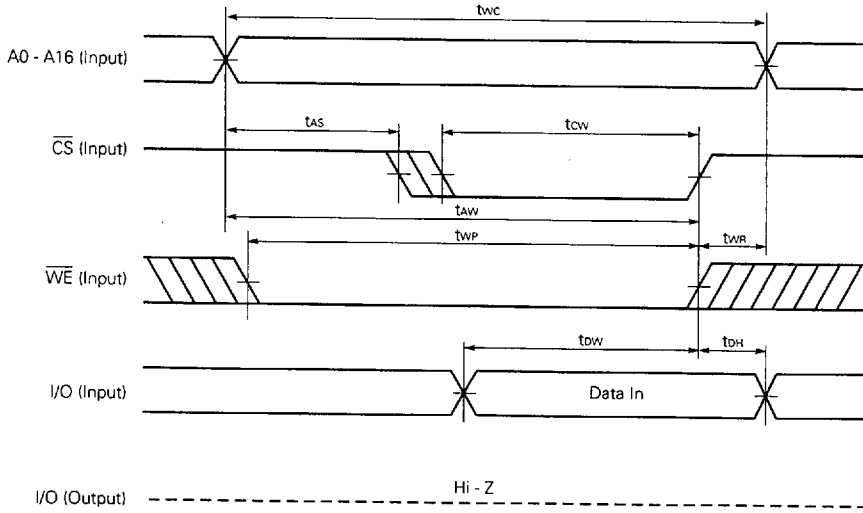
Caution \overline{CS} or \overline{WE} should be fixed to high level during address transition.

Remark 1. Write operation is done during the overlap time of a low level \overline{CS} and a low level \overline{WE} .

2. During t_{whz}, I/O pins are in the output state, therefore the input signals of opposite phase to the output must not be applied.

3. When \overline{WE} is at low level, the output state is always Hi-Z. When \overline{WE} is at high level, read operation is executed. Therefore \overline{OE} should be at high level to make the output state Hi-Z.

Write Cycle Timing Chart 2 (\overline{CS} Controlled)

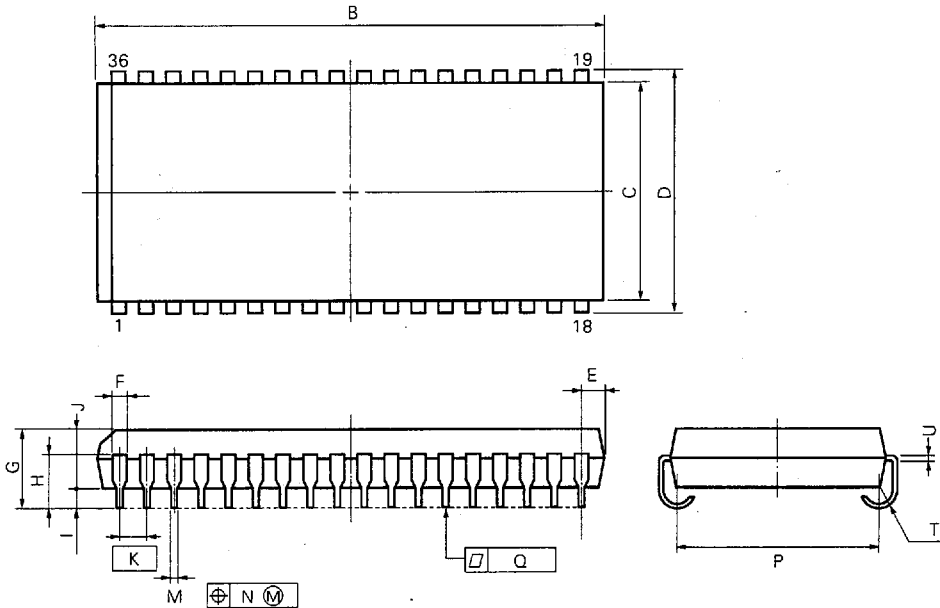


Caution \overline{CS} or \overline{WE} should be fixed to high level during address transition.

Remark Write operation is done during the overlap time of a low level \overline{CS} and a low level \overline{WE} .

Package Drawing

36 PIN PLASTIC SOJ (400 mil)



NOTE

Each lead centerline is located within 0.12 mm (0.005 inch) of its true position (T.P.) at maximum material condition.

P36LE-400A

ITEM	MILLIMETERS	INCHES
B	23.6±0.2	0.929±0.008
C	10.16	0.400
D	11.18±0.2	0.440±0.008
E	1.005±0.1	0.040 ^{+0.004} _{-0.005}
F	0.74	0.029
G	3.5±0.2	0.138±0.008
H	2.545±0.2	0.100±0.008
I	0.8 MIN.	0.031 MIN.
J	2.6	0.102
K	1.27 (T.P.)	0.050 (T.P.)
M	0.40±0.10	0.016 ^{+0.004} _{-0.005}
N	0.12	0.005
P	9.4±0.20	0.370±0.008
Q	0.1	0.004
T	R 0.85	R 0.033
U	0.20 ^{+0.10} _{-0.05}	0.008 ^{+0.004} _{-0.002}

RECOMMENDED SOLDERING CONDITIONS

Please consult with our sales offices for soldering conditions of the μPD431009.

TYPE OF SURFACE MOUNT DEVICE

μPD431009LE: 36-pin plastic SOJ (400 mil)